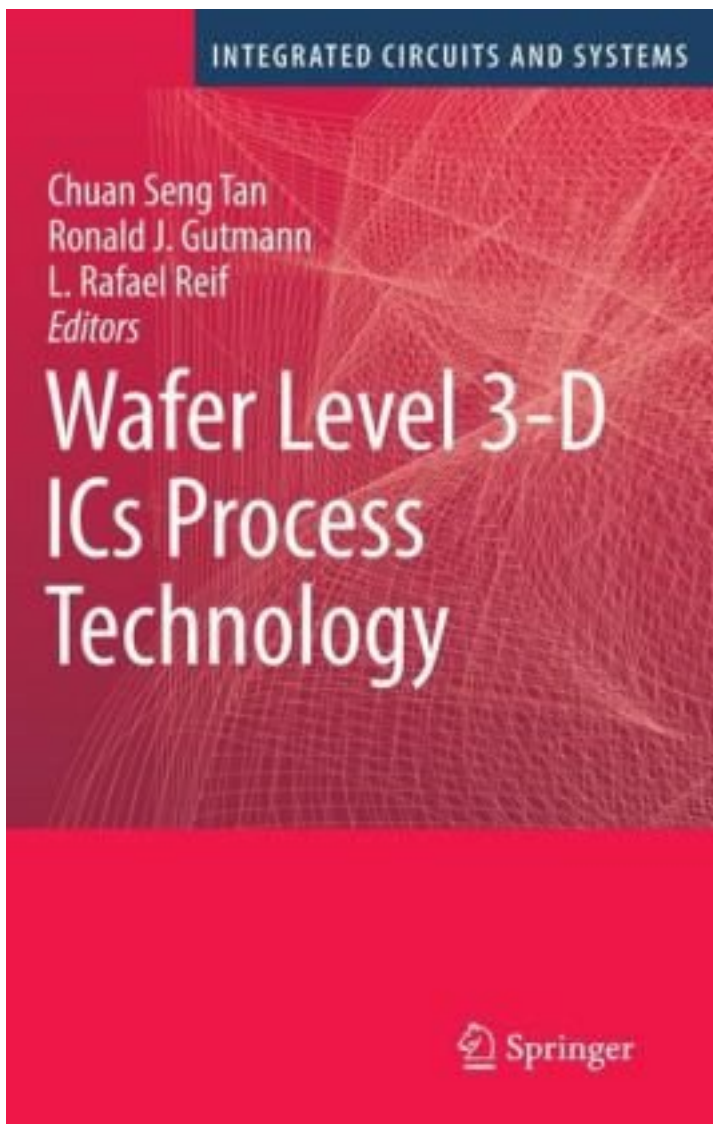


Wafer Level 3-D Ics Process Technology



[Wafer Level 3-D Ics Process Technology_ 下载链接1_](#)

著者: Tan, Chuan Seng (EDT)/ Gutmann, Ronald J. (EDT)/ Reif, L. Rafael (EDT)/ List, Scott (FRW)

出版者:

出版时间: 2008-9

装帧:

isbn: 9780387765327

This book focuses on foundry-based process technology that enables the fabrication of 3-D ICs. The core of the book discusses the technology platform for pre-packaging wafer level 3-D ICs. However, this book does not include a detailed discussion of 3-D ICs design and 3-D packaging. This is an edited book based on chapters contributed by various experts in the field of wafer-level 3-D ICs process technology. They are from academia, research labs and industry.

作者介绍:

目录:

[Wafer Level 3-D Ics Process Technology_ 下载链接1_](#)

标签

评论

[Wafer Level 3-D Ics Process Technology_ 下载链接1_](#)

书评

[Wafer Level 3-D Ics Process Technology_ 下载链接1_](#)